



**ENVIRONMENTAL AND PACKAGE TESTING DATA FOR PLCC**

<b>Stress</b>	<b>Sample Size</b>	<b>Device Hr./Cyc</b>	<b>Condition</b>	<b>Total Fails</b>	<b>Fail Percentage</b>
HAST	315	31,500	130°C, 85%RH	0	0.00
Pressure Pot	1,075	103,200	121°, 15 PSIG	0	0.00
Solder DUNK	110	330	260°C, 10SEC	0	0.00
Solderability	165	1,440	883 M2003	0	0.00
Temp Cycle	1,175	432,500	-65°C-150°C	0	0.00